



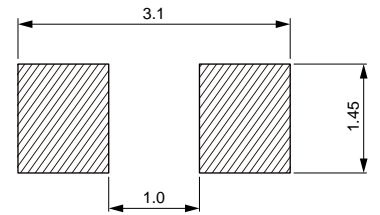
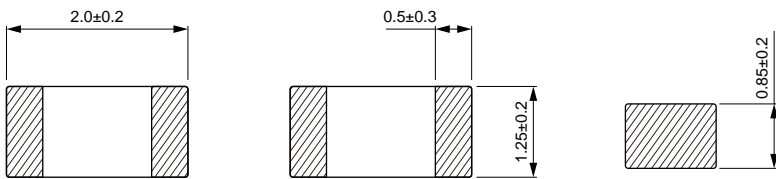
# Chip Ferrite Bead High Current Type Size 0805



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Dimensions: [mm]

Land Pattern: [mm]



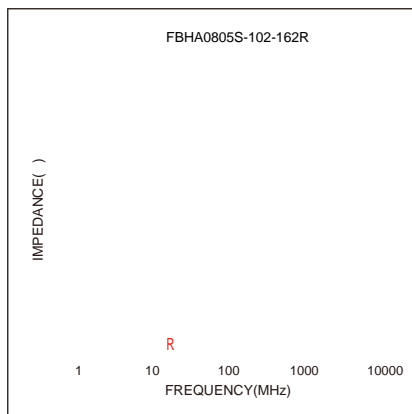
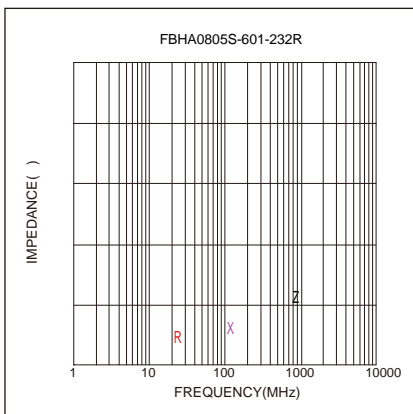
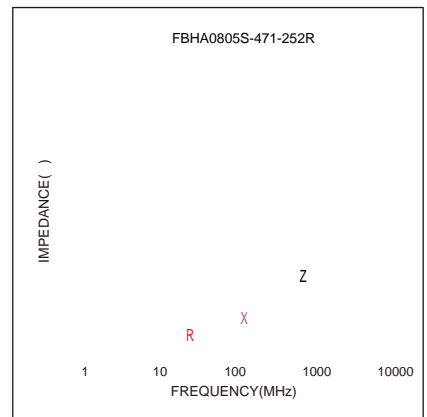
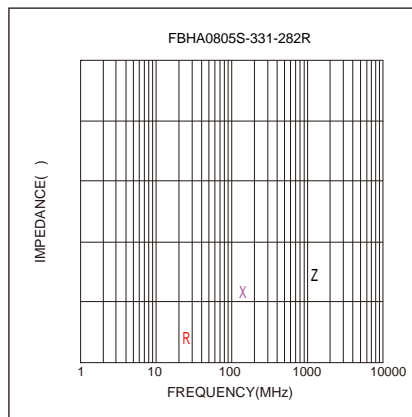
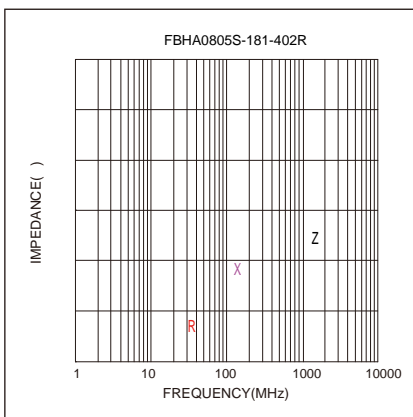
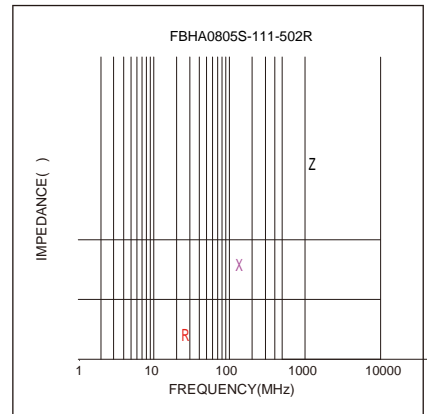
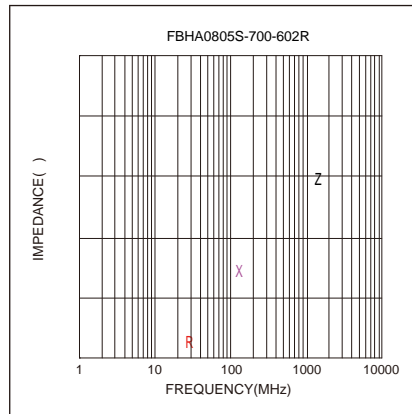
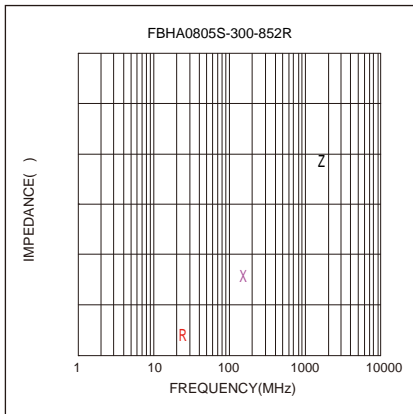
## Electrical Properties:

Part No	Impedance @ 100MHz	Tolerance	DC Resistance Max.	Temperature Rise Current Max.

Temperature Rise Current: The actual value of DC current when the temperature rise is  $\Delta T=40^{\circ}\text{C}$

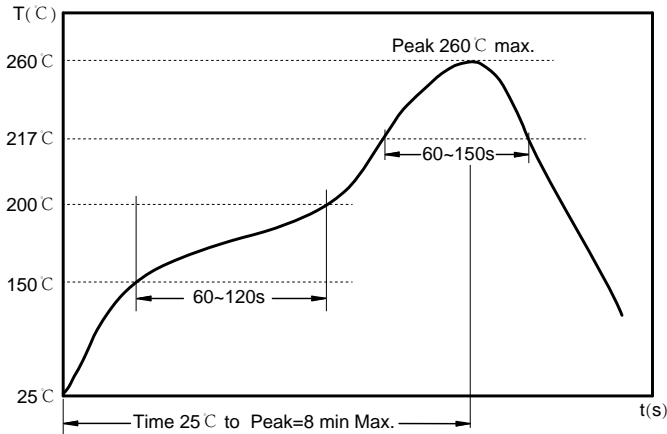


# Typical Electrical Characteristics:





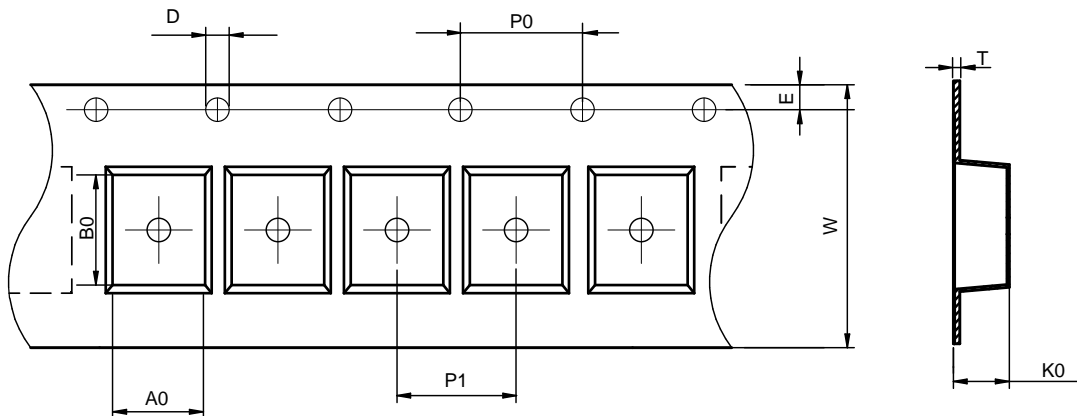
## Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.  
 Allowed time above 217 °C: 60~150 sec.  
 Max temperature: 260 °C.  
 Allowed Reflow time: 3x max.

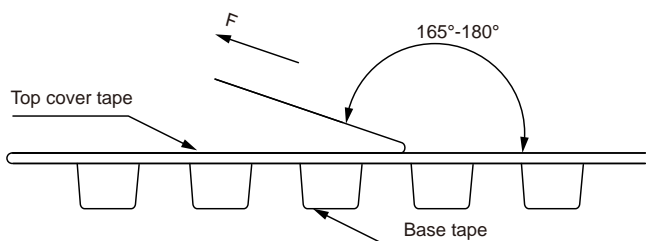
## Packaging Information:

### Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
FBHA0805S	1.30±0.05	2.10±0.05	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.3	0.95±0.05	1.75±0.1	0.95±0.05

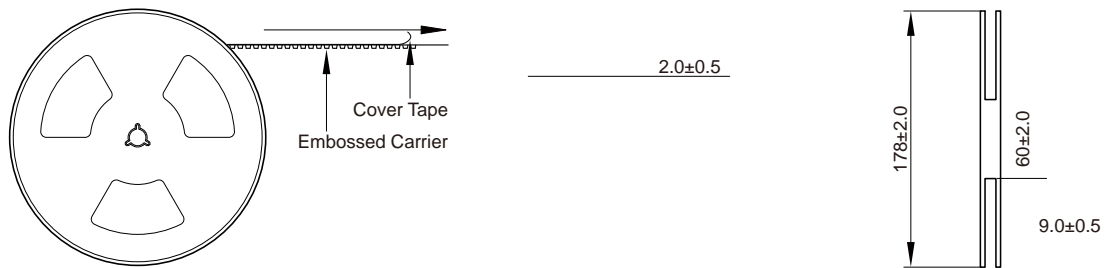
### Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.58 N



## Reel Dimension: [mm]



## Cautions and Warnings:

### Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature:  $-5$  to  $35^{\circ}\text{C}$ , humidity: 75% RH Max). If the storage period elapses, the soldering of the

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### Operation Instructions:

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